

In re Application of:
Keith Weinstein
Application No.: 10/601,139
Filed: June 20, 2003
Page 2

PATENT
Atty Docket No.: PMW1110-2

Amendments to the Claims

Please amend claims 1-7 and 9 as indicated in the listing of claims.

Please cancel claims 10-16 and 18-19 without prejudice.

Claims 8 and 17 were previously canceled without prejudice.

Claims 1, 3-7 and 9 have been allowed in the Advisory Action mailed on June 27, 2006.

The listing of claims will replace all prior versions, and listings of claims in the application.

Listing of Claims:

1. (Currently amended) A solder composition for assembling, repairing or sizing jewelry comprising of about 25% to 92% by weight gold mixture and about 2% to 14% by weight of an alloy consisting of gallium, indium, and copper in a respective weight ratio of approximately 6:3:1, wherein the solder composition has a melting temperature in a range from about 1000°F to about 1550°F.

2. (Currently amended) The solder composition of claim 1, wherein the ~~about 25% to 92% by weight gold further comprises a mixture~~ comprises of about 8% to 75% silver, about 1% to 66% copper, about 5% to 31% zinc and about 0% to 35% nickel.

3. (Currently amended) The solder composition of claim 1, wherein the ~~composition~~ mixture is about 25% by weight gold.

4. (Currently amended) The solder composition of claim 1, wherein the ~~composition~~ mixture is about 41.6% by weight gold.

5. (Currently amended) The solder composition of claim 1, wherein the ~~composition~~ mixture is about 58.3% by weight gold.

In re Application of:
Keith Weinstein
Application No.: 10/601,139
Filed: June 20, 2003
Page 3

PATENT
Atty Docket No.: PMW1110-2

6. (Currently amended) The solder composition of claim 1, wherein the ~~composition~~
mixture is about 75% by weight gold.

7. (Currently amended) The solder composition of claim 1, wherein the ~~composition~~
mixture is about 91.6% by weight gold.

8. (Canceled).

9. (Currently amended) A The solder composition ~~according to~~ of claim 1, wherein
the solder composition has a melting temperature in the range from about 1100°F to 1550°F.

10.-16. (Canceled).

17. (Canceled).

18.-19. (Canceled).